Amendments to the Abstract:

ABSTRACT

~~The invention concerns a~~ A method for populating and soldering a circuit board, which is populated with a wired, electrical component having at least one connection wire or pin and a housing or casing thermally critical for conventional, automatic soldering methods. ~~The invention additionally concerns~~ Additionally, a reflow oven for the soldering of the circuit board and a circuit board for such method are discussed. ~~The invention enables the soldering~~ Soldering of the thermally critical component in the reflow oven is enabled by using the circuit board itself for the thermal shielding of the thermally critical THT-components against the heat energy acting on the circuit board and required for the soldering. The circuit boards [[66]] are placed on frames [[67]] for this purpose, for example, and transported through the reflow oven [[60]] in such a manner that the thermally critical components are arranged on the under side of the circuit board [[66]] facing away from the heat energy.
~~(Fig. 7)~~